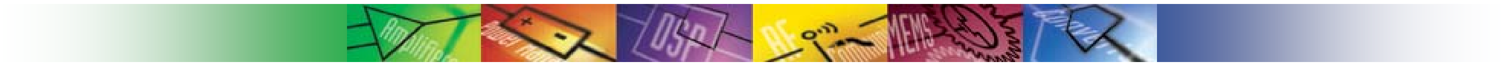

Product / Package Information	
Package	SSOP
Body Size	
Lead Count	20
Terminal Finish	100Sn
MS Number	MS010653B

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.95 E-02	87.30	873000	52.96	529583
Thermosets	Phenol Resin	Proprietary	4.61 E-03	4.50	45000	2.73	27298
Thermosets	Epoxy Resin 1	Proprietary	3.08 E-03	3.00	30000	1.82	18199
Thermosets	Epoxy Resin 2	Proprietary	3.08 E-03	3.00	30000	1.82	18199
Others	Others	Proprietary	2.05 E-03	2.00	20000	1.21	12132
Other inorganic materials	Carbon Black	1333-86-4	2.05 E-04	0.20	2000	0.12	1213
Subtotal			1.03 E-01	100.00	1000000	60.66	606624

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.95 E-02	97.57	975706	35.24	352428
Copper & its alloys	Iron	7439-89-6	1.39 E-03	2.28	22789	0.82	8231
Copper & its alloys	Zinc	7440-66-6	7.71 E-05	0.13	1263	0.05	456
Copper & its alloys	Phosphorus	7723-14-0	1.48 E-05	0.02	242	0.01	88
Subtotal			6.10 E-02	100.00	1000000	36.12	361203

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.17 E-04	100.0	1000000	0.36	3649

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.73 E-03	100.0	1000000	1.62	16155

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.00 E-04	100.00	1000000	0.12	1184

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.59 E-03	100.0	1000000	0.94	9410

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.42 E-04	80.50	805000	0.14	1429
Other organic materials	Carbocyclic Acrylates	Proprietary	3.00 E-05	10.00	100000	0.02	178
Other organic materials	Bismaleimide resin	Proprietary	9.00 E-06	3.00	30000	0.01	53
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	9.00 E-06	3.0	30000	0.01	53
Others	Additive	Proprietary	9.00 E-06	3.0	30000	0.01	53
Other organic materials	Dicumyl peroxide	80-43-3	1.50 E-06	0.5	5000	0.001	9
Subtotal			3.00 E-04	100.00	1000000	0.18	1775

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.69 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	SSOP
Body Size	
Lead Count	20
Terminal Finish	SnPb
MS Number	MS010681B

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.95 E-02	87.30	873000	52.96	529583
Thermosets	Phenol Resin	Proprietary	4.61 E-03	4.50	45000	2.73	27298
Thermosets	Epoxy Resin 1	Proprietary	3.08 E-03	3.00	30000	1.82	18199
Thermosets	Epoxy Resin 2	Proprietary	3.08 E-03	3.00	30000	1.82	18199
Others	Others	Proprietary	2.05 E-03	2.00	20000	1.21	12132
Other inorganic materials	Carbon Black	1333-86-4	2.05 E-04	0.20	2000	0.12	1213
Subtotal			1.03 E-01	100.00	1000000	60.66	606624

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.95 E-02	97.57	975706	35.24	352428
Copper & its alloys	Iron	7439-89-6	1.39 E-03	2.28	22789	0.82	8231
Copper & its alloys	Zinc	7440-66-6	7.71 E-05	0.13	1263	0.05	456
Copper & its alloys	Phosphorus	7723-14-0	1.48 E-05	0.02	242	0.01	88
Subtotal			6.10 E-02	100.00	1000000	36.12	361203

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.17 E-04	100.0	1000000	0.36	3649

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.32 E-03	85.00	850000	1.37	13732
Tin & its alloys	Lead	7439-92-1	4.09 E-04	15.00	150000	0.24	2423
Subtotal			2.73 E-03	100.0	1000000	1.62	16155

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.00 E-04	100.00	1000000	0.12	1184

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.59 E-03	100.0	1000000	0.94	9410

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.42 E-04	80.50	805000	0.14	1429
Other organic materials	Carbocyclic Acrylates	Proprietary	3.00 E-05	10.00	100000	0.02	178
Other organic materials	Bismaleimide resin	Proprietary	9.00 E-06	3.00	30000	0.01	53
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	9.00 E-06	3.0	30000	0.01	53
Others	Additive	Proprietary	9.00 E-06	3.0	30000	0.01	53
Other organic materials	Dicumyl peroxide	80-43-3	1.50 E-06	0.5	5000	0.001	9
Subtotal			3.00 E-04	100.00	1000000	0.18	1775

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.69 E-01**	**100.00**	**1000000**

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ANALOG DEVICES

ADI Proprietary